Compliant with IEC 62474/ D9.00 Compliant to IEC 61249-2-21:2003

MICROCHIP Semiconductor Device Type: E8A 020 SOIC .300 NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				J-STD-609A Product Marking and/or Pkg. Labeling e4
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	383.37	(mg) Total	Mold Compound	% ot Total Weight	70.89
Silica, vitreous	60676-86-0	Mold Compound	60.257	325.867	602.565		Silica, vitreous	60676-86-0	85.00	
Epoxy Resin	Trade Secret	Mold Compound	4.342	23.482	43.420		Epoxy Resin	Trade Secret	6.13	
Phenolic Resin	Trade Secret	Mold Compound	4.342	23.482	43,420		Phenolic Resin	Trade Secret	6.13	
Epoxy, Cresol Novolac	29690-82-2	Mold Compound	1.737	9.393	17.368		Epoxy, Cresol Novolac	29690-82-2	2.45	
Carbon Black	1333-86-4	Mold Compound	0.213	1.150	2,127		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	25.624	138.572	256,235			Total	100.00	
Iron	7439-89-6	Lead Frame	0.039	0.208	385	138.88	(mg) Total	Lead Frame	% of Total Weight	25.68
Phosphorous	7723-14-0	Lead Frame	0.010	0.056	103		Copper	7440-50-8	99.78	
Zinc (Metal)	7440-66-6	Lead Frame	0.008	0.042	77		Iron	7439-89-6	0.15	
Silver	7440-22-4	Die Attach	0.407	2.201	4,070		Phosphorous	7723-14-0	0.04	
Epoxy resin	68475-94-5	Die Attach	0.127	0.684	1,265		Zinc (Metal)	7440-66-6	0.03	
Copper(II) oxide	1317-38-0	Die Attach	0.017	0.089	165			Total	100.00	
Silicon	7440-21-3	Chip (Die)	0.980	5.300	9,800	2.97	(mg) Total	Die Attach	% of Total Weight	0.55
Gold	7440-57-5	Wire Bond	0.500	2.704	5,000		Silver	7440-22-4	74.00	
Nickel	7440-02-0	Plating on external leads (pins)	1.260	6.814	12,600		Epoxy resin	68475-94-5	23.00	
Palladium	7440-05-3	Plating on external leads (pins)	0.070	0.379	700		Copper(II) oxide	1317-38-0	3.00	
Gold	7440-57-5	Plating on external leads (pins)	0.070	0.379	700			Total	100.00	
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